

General Description

The WSF30100 is the highest performance trench N-ch MOSFET with extreme high cell density, which provide excellent R_{DS(on)} and gate charge for most of the synchronous buck converter applications .

The WSF30100 meet the RoHS and Green Product requirement , 100% EAS guaranteed with full function reliability approved.

Features

Advanced high cell density Trench technology
 Super Low Gate Charge
 Excellent CdV/dt effect decline
 100% EAS Guaranteed
 Green Device Available

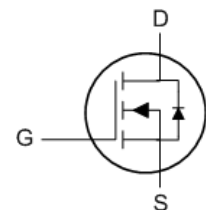
Product Summary

BVDSS	R _{DS(on)}	I _D
30V	2.5mΩ	100A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter
- Networking DC-DC Power System
- Power Tool Application

TO-252 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ^{1,7}	100	A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ^{1,7}	80	A
I _{DM}	Pulsed Drain Current ²	310	A
EAS	Single Pulse Avalanche Energy ³	378	mJ
I _{AS}	Avalanche Current	70.2	A
P _D @T _C =25°C	Total Power Dissipation ⁴	89.3	W
T _{STG}	Storage Temperature Range	-55 to 175	°C
T _J	Operating Junction Temperature Range	-55 to 175	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	62	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	1.4	°C/W

Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	30---	---	V	
ΔBV _{DSS} /ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25°C, I _D =1mA	---	0.022	---	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =20A	---	2.5	3	mΩ
		V _{GS} =10V, I _D =15A	---	3.2	4	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1	1.5	2.5	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	-6.1	---	mV/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =24V, V _{GS} =0V, T _J =25°C	---	---	2	uA
		V _{DS} =24V, V _{GS} =0V, T _J =55°C	---	---	10	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =5V, I _D =30A	---	60	---	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	0.9	1.8	Ω
Q _g	Total Gate Charge (4.5V)	V _{DS} =15V, V _{GS} =10V, I _D =20A	---	56.9	---	nC
Q _{gs}	Gate-Source Charge		---	13.8	---	
Q _{gd}	Gate-Drain Charge		---	23.5	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =15V, V _{GS} =10V, R _G =3.3Ω, I _D =1A	---	20.1	---	ns
T _r	Rise Time		---	6.3	---	
T _{d(off)}	Turn-Off Delay Time		---	124.6	---	
T _f	TFall Time		---	15.8	---	
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1MHz	---	5935	---	pF
C _{oss}	Output Capacitance		---	725	---	
C _{rss}	Reverse Transfer Capacitance		---	538	---	

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =25V, L=0.1mH, I _{AS} =20A	69	---	---	mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current ^{1,6}	V _G =V _D =0V, Force Current	---	---	40	A
I _{SM}	Pulsed Source Current ^{2,6}		---	---	310	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V, I _S =A, T _J =25°C	---	---	1.2	V

Note :

- The data tested by surface mounted on a 1 inch²FR-4 board with 20Z copper, t<10sec.
- The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- The EAS data shows Max. rating. The test condition is V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=20A
- The power dissipation is limited by 150°C junction temperature
- The Min. value is 100% EAS tested guarantee.
- The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.
- Package limitation current is 100A.

Typical Characteristics

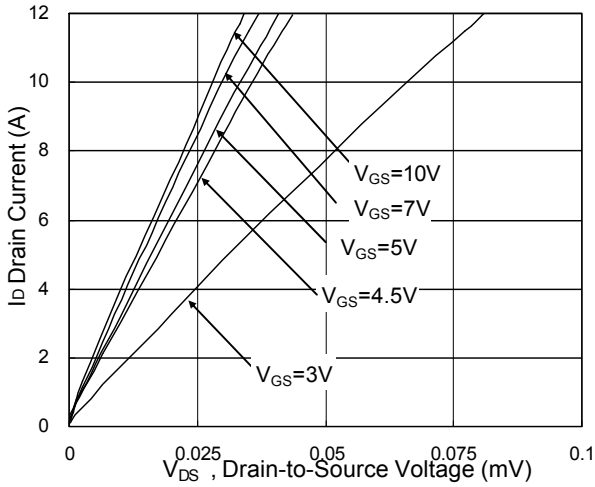


Fig.1 Typical Output Characteristics

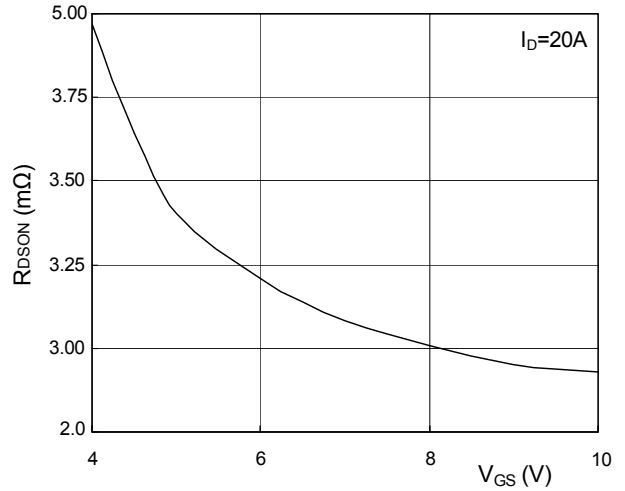


Fig.2 On-Resistance v.s Gate- Source

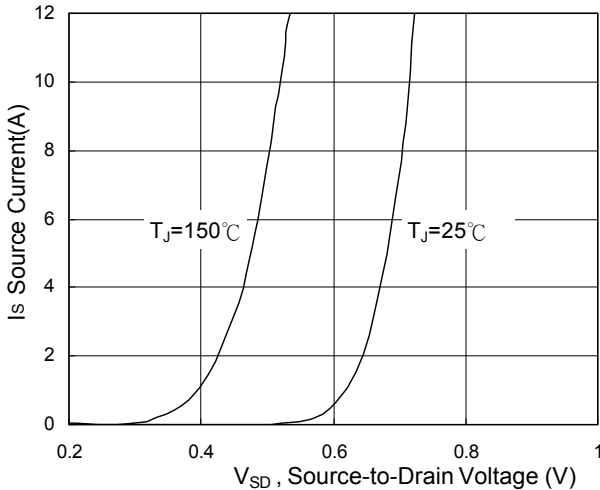


Fig.3 Forward Characteristics of Reverse

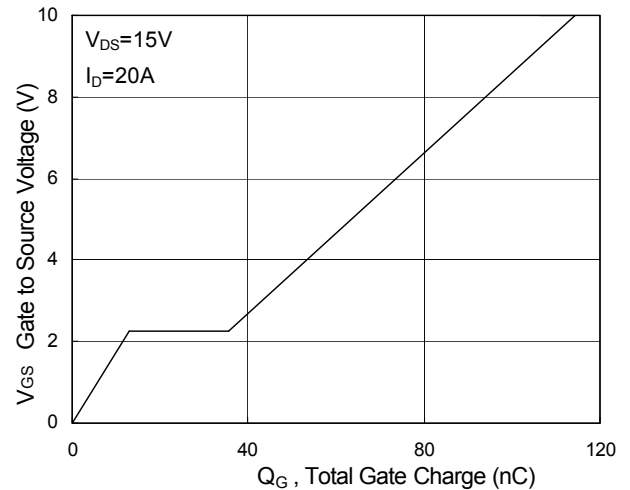


Fig.4 Gate-Charge Characteristics

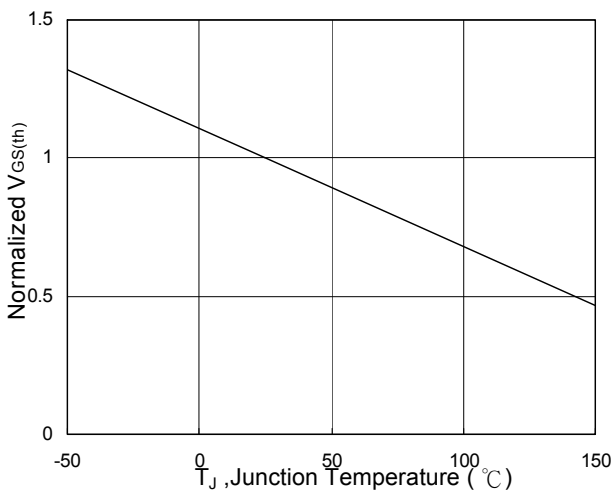


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

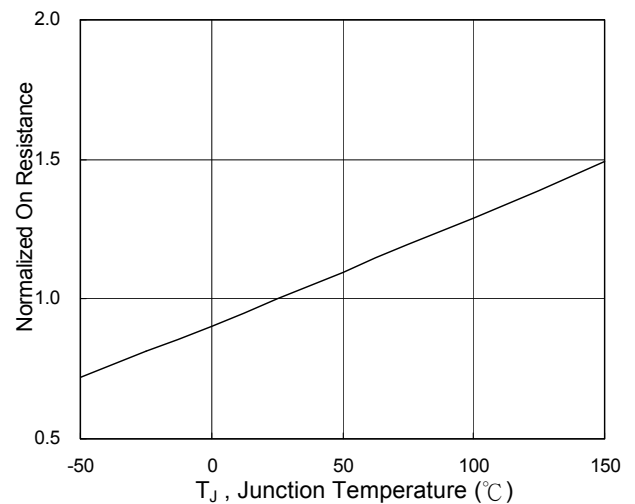


Fig.6 Normalized R_{DSON} v.s T_J

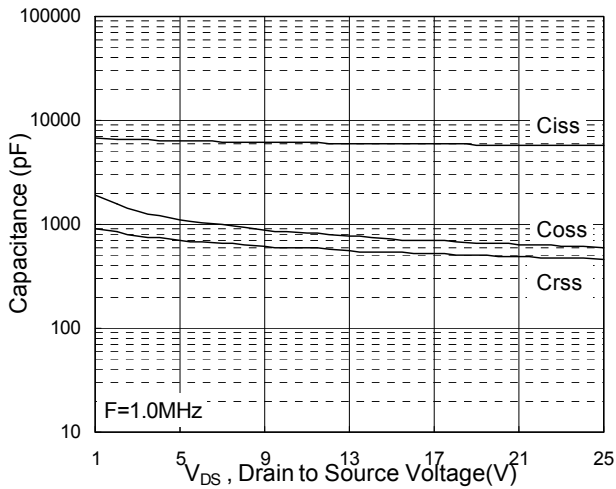


Fig.7 Capacitance

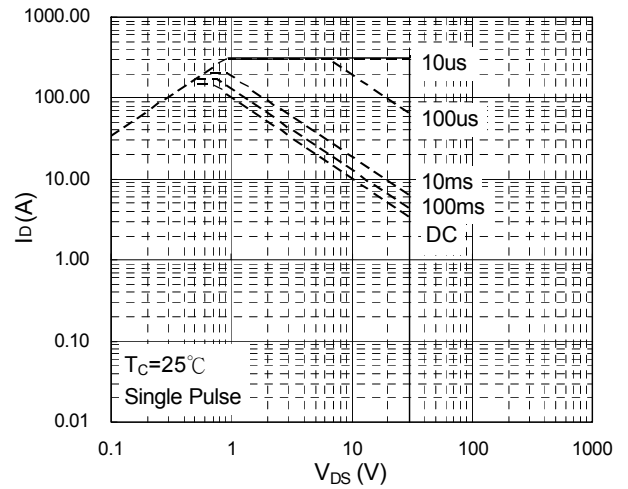


Fig.8 Safe Operating Area

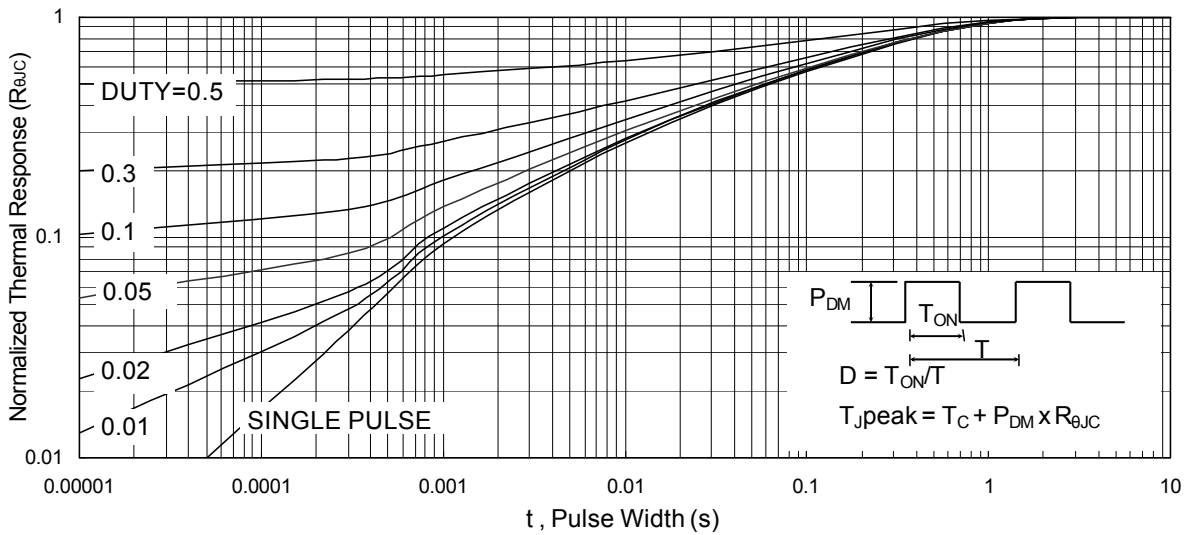


Fig.9 Normalized Maximum Transient Thermal

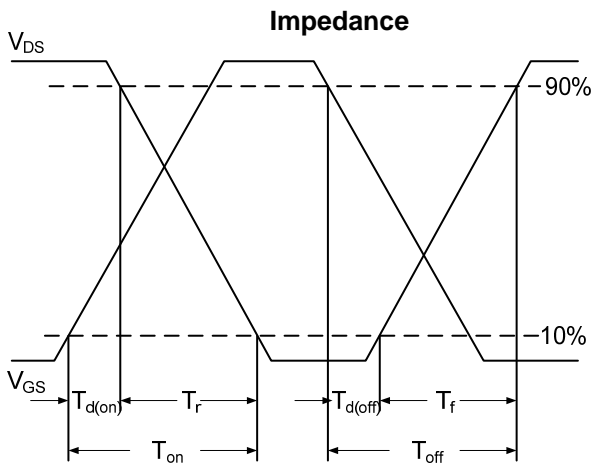


Fig.10 Switching Time Waveform

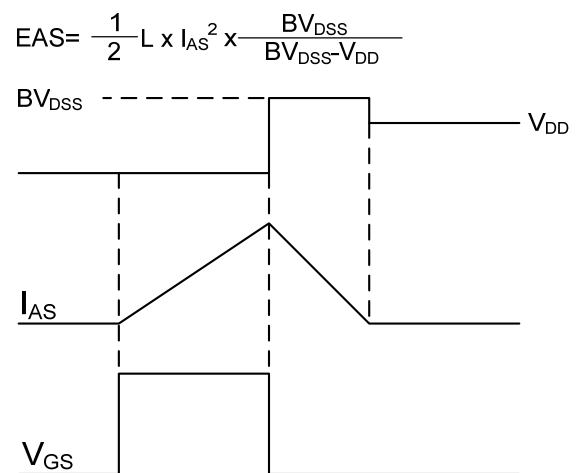


Fig.11 Unclamped Inductive Waveform

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